EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L21	430	measur$4 with acceleration with contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:29
L22	15633	324/754-765,158.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:30
L23	8	L22 and 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:40
L24	46968	test$4 near5 (semiconductor adj substrate or IC or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:41
L25	8	21 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:44
L26	1	test$4 near5 movement adj sensitive adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:47
L27	3	test$4 near5 movement near5 sensitive with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 17:47
L28	1628	sandwich and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:22
L29	55	22 and 28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:24

L30	1772	24 and blade	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:26
L31	9	28 and 30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:25
L32	357	24 and bladder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:53
L33	60	22 and 32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/14 18:52
S1	36085	test$4 near5 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:50
S2	1280	test$4 near3 electrical adj characteristic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:51
S3	186	S1 and S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:51
S4	9	S3 and acceleration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:56
S5	67988	test$4 near5 (integrated adj circuit or IC! or chip or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:56
S6	3027	S5 and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:56

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S7	230	S6 and acceleration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 17:57
S8	18	S7 and 324/765,158.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:04
S9	5238	324/765,158.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:04
S10	2543	test$4 near5 wafer and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:04
S11	336	S9 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:05
S12	2501	linear adj acceleration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:05
S13	0	S11 and S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:06
S14	37	S11 and accelerat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 18:06
S15	9094	324/754-765,158.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:39
S16	67988	test$4 near5 (integrated adj circuit or IC! or chip or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:39

S17	5095	S16 and S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:40
S18	3598	control$4 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:40
S19	692	S18 and chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:41
S20	610	S19 and (accelerat$4 or mov$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:41
S21	244	S20 and (linear or rotary or oscillat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 20:42
S22	0	(measur$4 or test$4 or detect$4) near5 (electrical adj characteristic) with mechanical$4 adj accelerat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 20:29
S23	30	(measur$4 or test$4 or detect$4) near5 (electrical adj characteristic) with accelerat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 20:33
S24	6506	(measur$4 or test$4 or detect$4) near5 (electrical adj characteristic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 20:33
S25	5136	324/158.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 20:34
S26	168	S24 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 20:35

EAST Search History

S27	8017	chuck and (probe or needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:14
S28	36	S26 and S27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:01
S29	4297	324/765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:02
S30	284	S24 and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:02
S31	54	S27 and S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:02
S32	3	("3963985" | "5124639" | "5325052").PN. OR ("6765401").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 21:12
S33	662989	(probe or needle or probe adj card)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:15
S34	173	S30 and S33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:15
S35	0	S34 and accelarat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:16
S36	16	S34 and accelerat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:18

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S37	59	S34 and pressure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:18
S38	60	S34 and pressur$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 21:18